



P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$ $I_D(A)$ Q		Q _g (Typ.)		
	0.066 at V _{GS} = - 4.5 V	- 9 ^a			
- 20	0.094 at V _{GS} = - 2.5 V	- 9 ^a	6 nC		
	0.130 at V _{GS} = - 1.8 V	- 9 ^a			

FEATURES

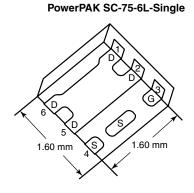
- · Halogen-free
- TrenchFET[®] Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-75 Package
 - Small Footprint Area
 - Low On-Resistance

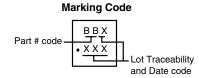


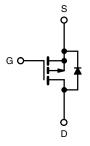
RoHS

APPLICATIONS

 Load Switch, PA Switch and Battery Switch for Portable Devices







Ordering Information: SiB411DK-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	5 T _A = 25 °C, unle	ss otherwise no	ted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 20	V	
Gate-Source Voltage		V _{GS} ± 8		v	
	T _C = 25 °C		- 9 ^a		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	1_	- 8.9 ^a		
Continuous Drain Current (1) = 150 °C)	T _A = 25 °C	l _D –	- 4.8 ^{b, c}		
	T _A = 70 °C		- 3.8 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	- 15		
Continuous Source-Drain Diode Current	T _C = 25 °C	la	- 9 ^a		
	T _A = 25 °C	ls –	- 2 ^{b, c}		
Maximum Power Dissipation	T _C = 25 °C		13		
	T _C = 70 °C	P _D	8.4	w	
	T _A = 25 °C	'D	2.4 ^{b, c}	VV	
	T _A = 70 °C		1.6 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R_{thJA}	41	51	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	7.5	9.5]	

Notes:

- a. Package limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SC-75 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 105 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-				L		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	ns/Tu		- 18			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.2		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	<u> </u>	
		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	15			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 3.3 A		0.055	0.066	+	
				0.077	0.094	Ω	
		V _{GS} = - 1.8 V, I _D = - 0.77 A		0.107	0.130	1	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 3.3 A		9.5		S	
Dynamic ^b		-					
Input Capacitance	C _{iss}	Viec .		470			
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		95		pF	
Reverse Transfer Capacitance	C _{rss}	, do ,		65			
Tieverse Transfer Capabilance		V _{DS} = - 10 V, V _{GS} = - 8 V, I _D = - 4.5 A		10	15	+	
Total Gate Charge	Q _g	V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 4.5 A		6	9	- nC	
Gate-Source Charge				0.9			
Gate-Drain Charge	Q _{gd}	56 1 46 1		1.4			
Gate Resistance	R _q	f = 1 MHz		7.5		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 2.1 \Omega$		40	60	- ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong -4.8 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		45	70		
Fall Time	t _f	, and the second		75	115		
Turn-On Delay Time	t _{d(on)}			5	10		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 2.1 \Omega$		10	15		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong -4.8 \text{ A}, V_{GEN} = -8 \text{ V}, R_q = 1 \Omega$		25	40		
Fall Time	t _f	Ç		10	15		
Drain-Source Body Diode Characterist	i -						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 9	Ι.	
Pulse Diode Forward Current	I _{SM}				15	A	
Body Diode Voltage	V_{SD}	I _S = - 3.8 A, V _{GS} = 0 V		- 0.85	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			20	40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	D		10	20	nC	
Reverse Recovery Fall Time t _a		$I_F = -3.8 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		15		†	
Reverse Recovery Rise Time	t _b			5		ns	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

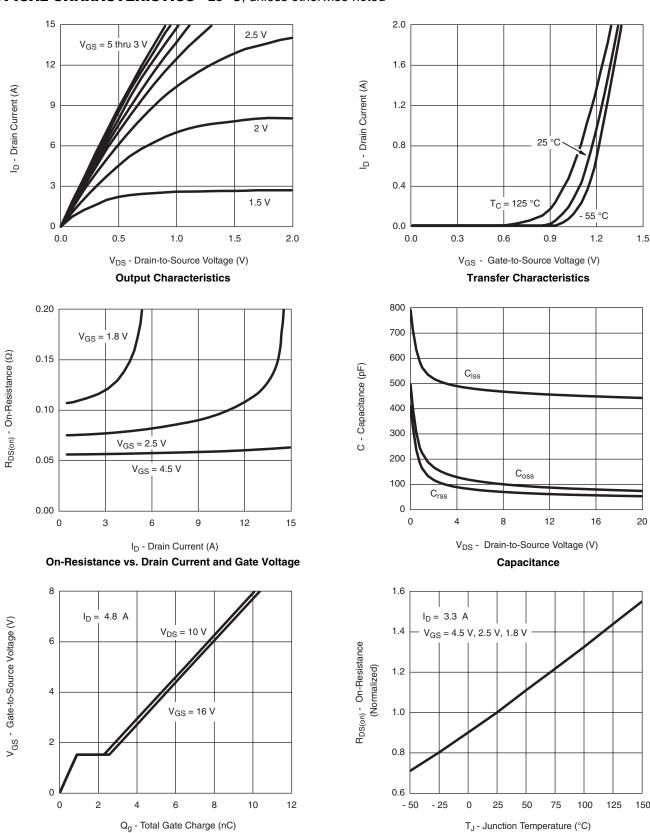
b. Guaranteed by design, not subject to production testing.







TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

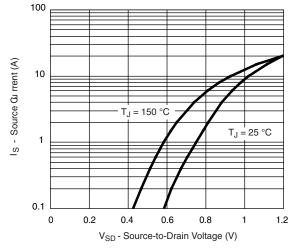


Gate Charge

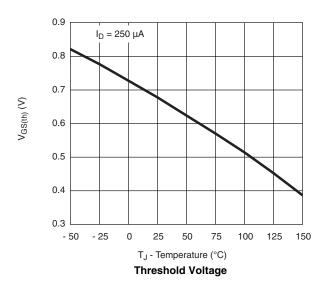
On-Resistance vs. Junction Temperature

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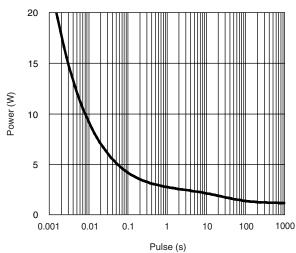


Soure-Drain Diode Forward Voltage

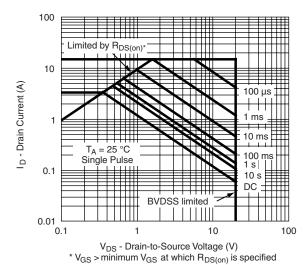


0.20 0.17 0.17 0.14 0.14 0.15 0.05 0 1 2 3 4 5 V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

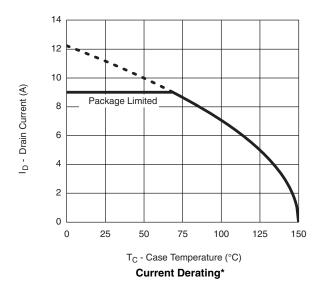


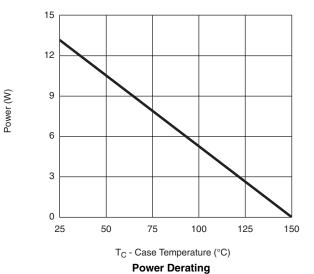
Safe Operating Area, Junction-to-Case





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



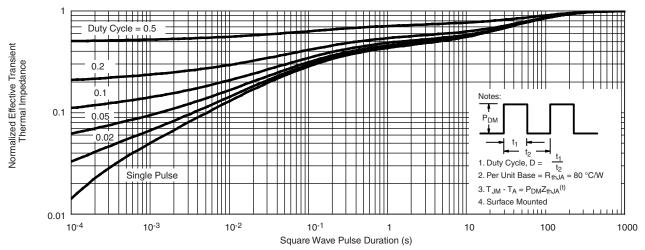


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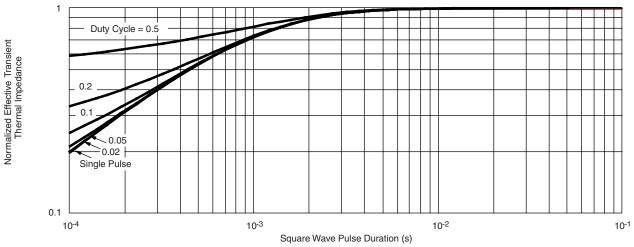
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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